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Lai(10) **Pub. No.: US 2024/0224470 A1**(43) **Pub. Date: Jul. 4, 2024**(54) **HEAT DISSIPATION ASSEMBLY AND
ELECTRIC DEVICE THEREOF**(71) Applicant: **GIGA-BYTE TECHNOLOGY CO.,
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(57)

ABSTRACT

A heat dissipation assembly and an electric device thereof are provided. An expansion card is fixed in the electric device. The heat dissipation assembly includes a heat dissipation unit and a quick release hook. A first guide block is provided on a first side of the heat dissipation unit, and a first positioning component is provided on the first guide block. The quick release hook includes a slide piece, a pressing component and a spring component. The slide piece includes a buckle slot and a first oblong hole. The first positioning component penetrates the first oblong hole and is provided on the first guide block, such that the slide piece is arranged on the first guide block. The spring component is compressed, a second end of the spring component abuts against the first side; and the spring component is released, the buckle slot abuts against a positioning column.

